

Type BMB-B Series

Key Features

Effective EMI Protection

Wide Frequency Characteristics

High soldering Heat Resistance

Various Package Sizes Available

Suited to a Variety of Applications

Terminal finish matte Sn over Cu/Ni underplate



These beads are designed for high speed applications. The BMB-B Series will minimise the attenuation of the signal wave form due to its sharp impedance characteristics. This series is offered in 04:02, 06:03 and 08:05 package sizes

Electrical Performance

Part Number	Impedance (Ω) at 100MHz	DC Resistance (Ω) maximum	Rated Current (mA) maximum
BMB-1E-0022B-N7	22 \pm 25%	0.20	300
BMB-1E-0047B-N7	47 \pm 25%	0.35	
BMB-1E-0075B-N7	75 \pm 25%	0.40	
BMB-1E-0120B-N7	120 \pm 25%		
BMB-1E-0220B-N7	220 \pm 25%	0.60	
BMB-1E-0300B-N7	300 \pm 25%	0.80	
BMB-1E-0022B-N7	22 \pm 25%	0.20	
BMB-1J-0030B-N7	30 \pm 25%	0.30	250
BMB-1J-0070B-N7	70 \pm 25%	0.40	200
BMB-1J-0120B-N7	120 \pm 25%		
BMB-1J-0240B-N7	240 \pm 25%		
BMB-1J-0300B-N7	300 \pm 25%	0.50	100
BMB-1J-0420B-N7	420 \pm 25%		200
BMB-1J-0600B-N7	600 \pm 25%	0.60	100
BMB-2A-0007B-N7	7 \pm 25%	0.10	300
BMB-2A-0030B-N7	30 \pm 25%	0.20	
BMB-2A-0070B-N7	70 \pm 25%	0.40	
BMB-2A-0100B-N7	100 \pm 25%		
BMB-2A-0120B-N7	120 \pm 25%	0.50	
BMB-2A-0200B-N7	200 \pm 25%		
BMB-2A-0300B-N7	300 \pm 25%		
BMB-2A-0450B-N7	450 \pm 25%		

Electrical Performance (continued)

Part Number	Impedance (Ω) at 100MHz * 50MHz * 30MHz	DC Resistance (Ω) maximum	Rated Current (mA) maximum
BMB-2A-0600B-N7	600 \pm 25%	0.60	200
BMB-2A-0750B-N7	750 \pm 25%	0.70	
BMB-2A-1000B-N7	1000 \pm 25%	0.80	

Operating temperature range - -55 ~ +125°C

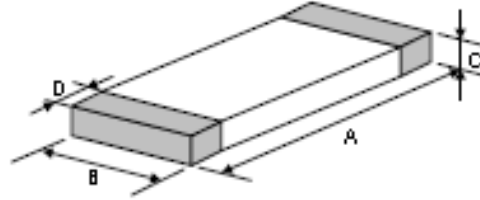
Temperature should be less than 25°C when rated current is applied.

Storage:

Temperature Range: -40 ~ +85°C

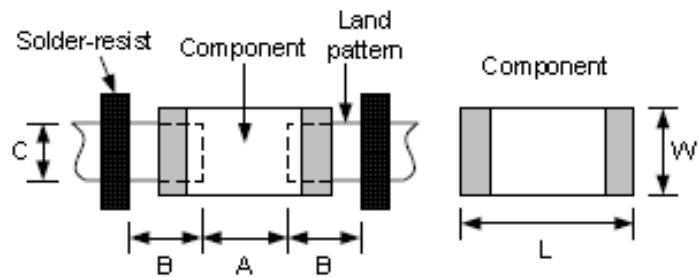
Humidity: Less than 75% RH

Product Dimensions



Size	A (mm)	B (mm)	C (mm)	D (mm)
0402	1.0 ±0.10	0.5 ±0.10	0.5 ±0.10	0.25 ±0.10
0603	1.6 ±0.15	0.8 ±0.15	0.8 ±0.15	0.3 ±0.20
0805	2.0 ±0.20	1.2 ±0.20	0.9 ±0.20	0.5 ±0.30

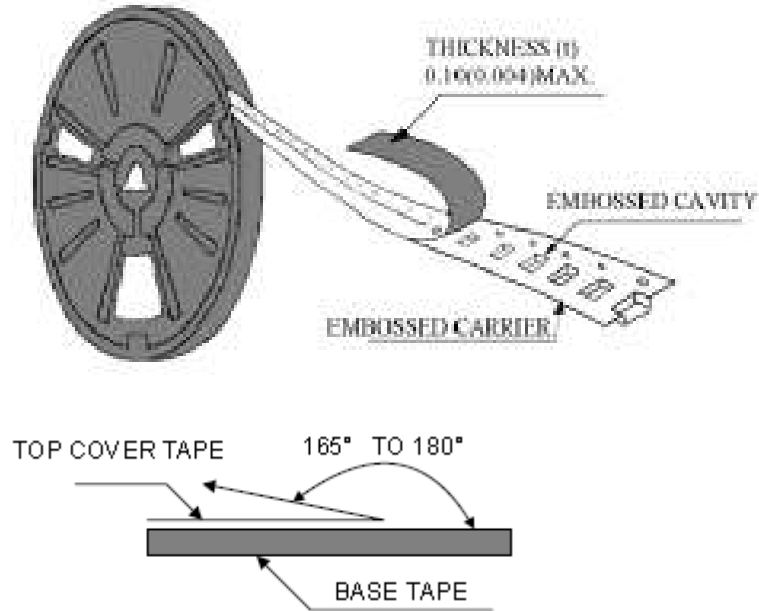
Recommended PCB Layout



Size	0402	0603	0805
Component	L	1.0	1.6
	W	0.5	0.8
A	0.45 ~ 0.55	0.6 ~ 0.8	0.8 ~ 1.2
B	0.40 ~ 0.50	0.6 ~ 0.8	0.8 ~ 1.2
C	0.40 ~ 0.50	0.6 ~ 0.8	0.9 ~ 1.6

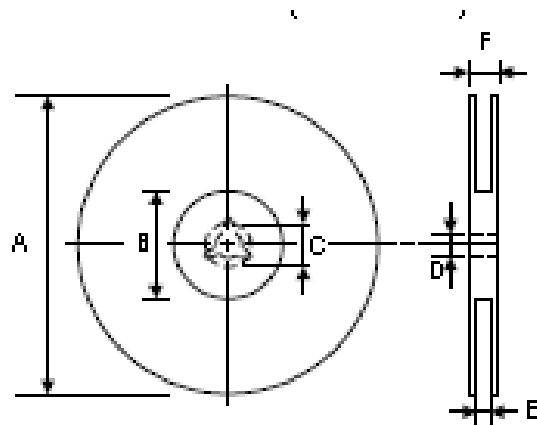
Packaging

Peel off force:

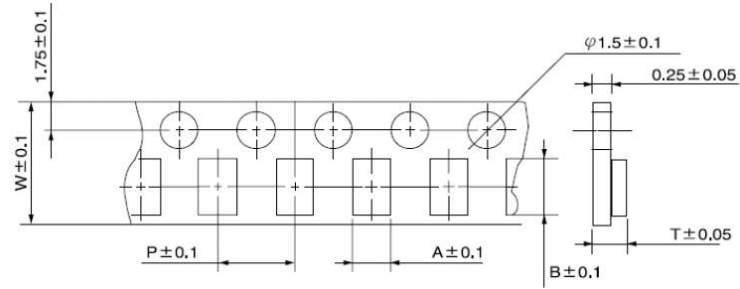


The force for peeling off cover tape is 10 grams in the direction shown

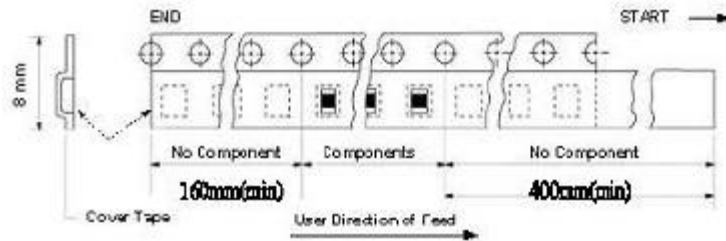
Dimensions (mm)



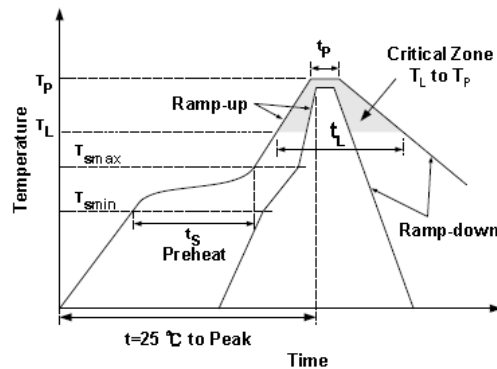
A	B	C	D	E	F
178 ±1	60 +0.5 -0.1	--	13 ±0.2	9 ±0.5	12 ±0.5



Size	A	B	W	P	T	Chips / Reel
0402	0.6	1.1	8	2	1.0	10000
0603	1.1	1.9	8	4	1.1	4000
0805	1.5	2.3	8	4	1.3	4000
1206	1.9	3.5	8	4	1.5	3000



Recommended Reflow Solder Profile



Profile Feature		Pb Free
Preheat	ts	60 ~ 180 seconds
	Tsmin	150°C
	Tsmax	200°C
Average Ramp up rate (Tsmax to Tp)		3°C/second max.
Time main above	Temperature (TL)	217°C
	Time (tL)	60 ~ 150 seconds
Peak Temperature (Tp)		250 ~ 260°C
Time within 5°C of actual peak temperature ((tp)		10 seconds
Ramp down rate		6°C/second max.
Time 25°C to peak temperature		8 minutes max.

Typical Characteristic Curves (T=25°C)

